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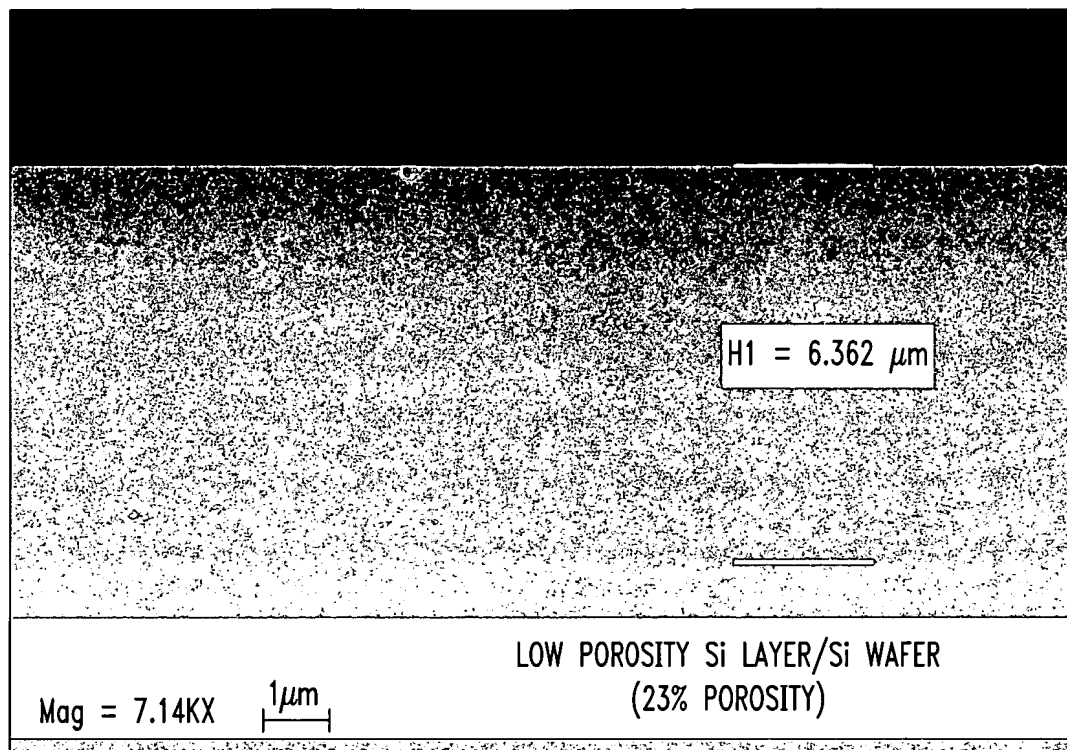
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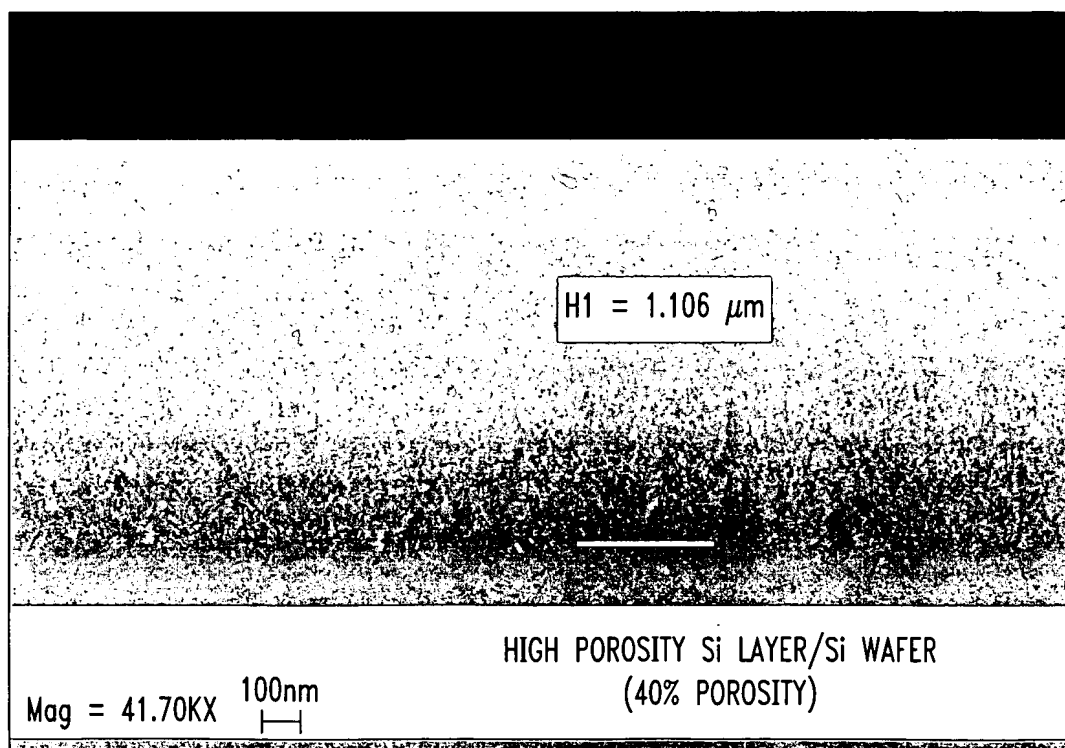
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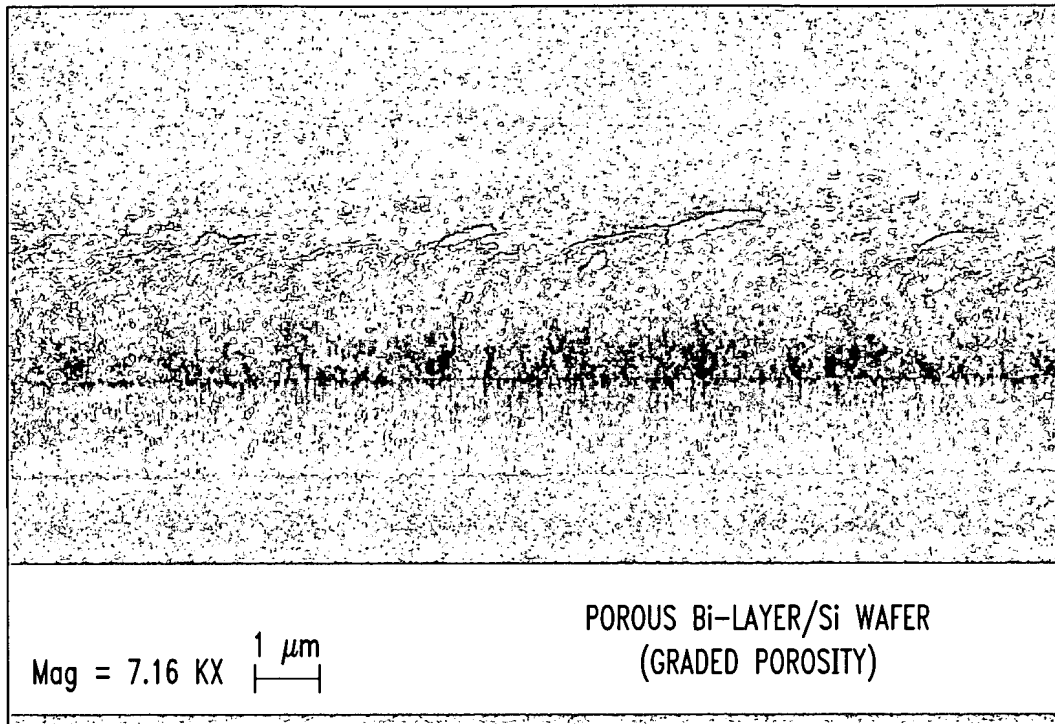
*FIG. 1a*



*FIG. 1b*

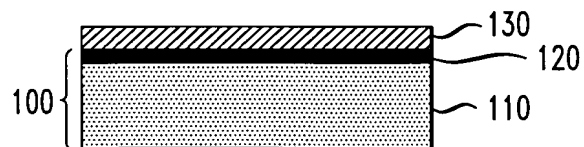


*FIG. 1c*



*FIG. 2*

SUBSTRATE BASED ON USE OF THE POROUS-Si LAYER AND  
SUBSEQUENT REGROWTH OF epi-Si LAYER TO CREATE SOI WAFERS



*FIG. 3*

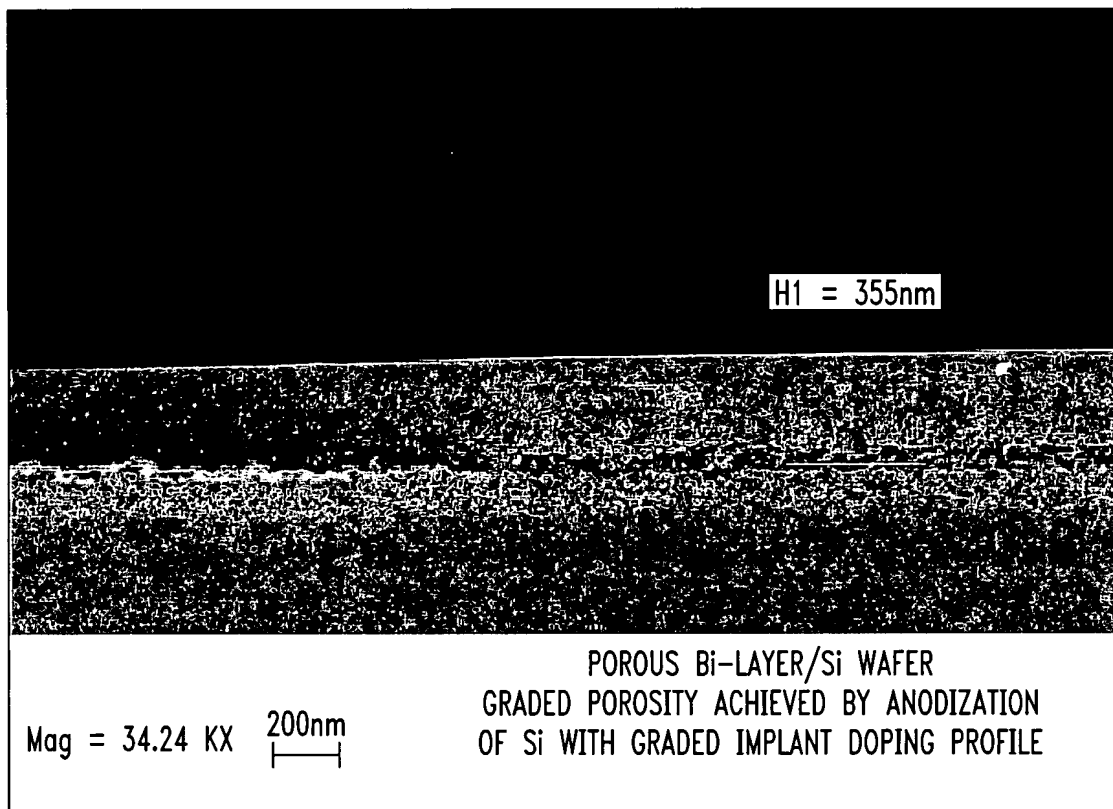
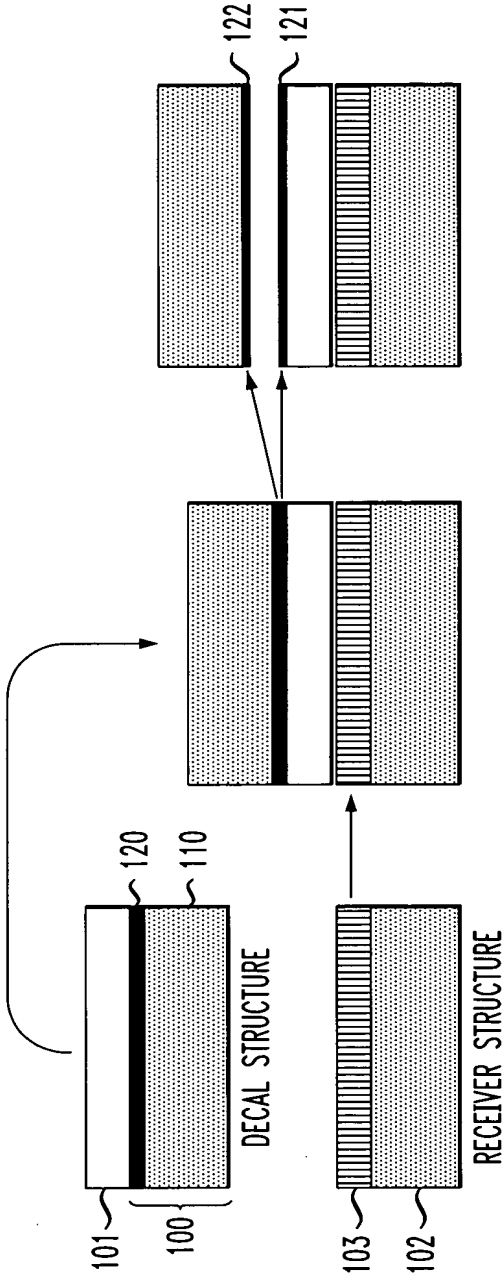


FIG. 4

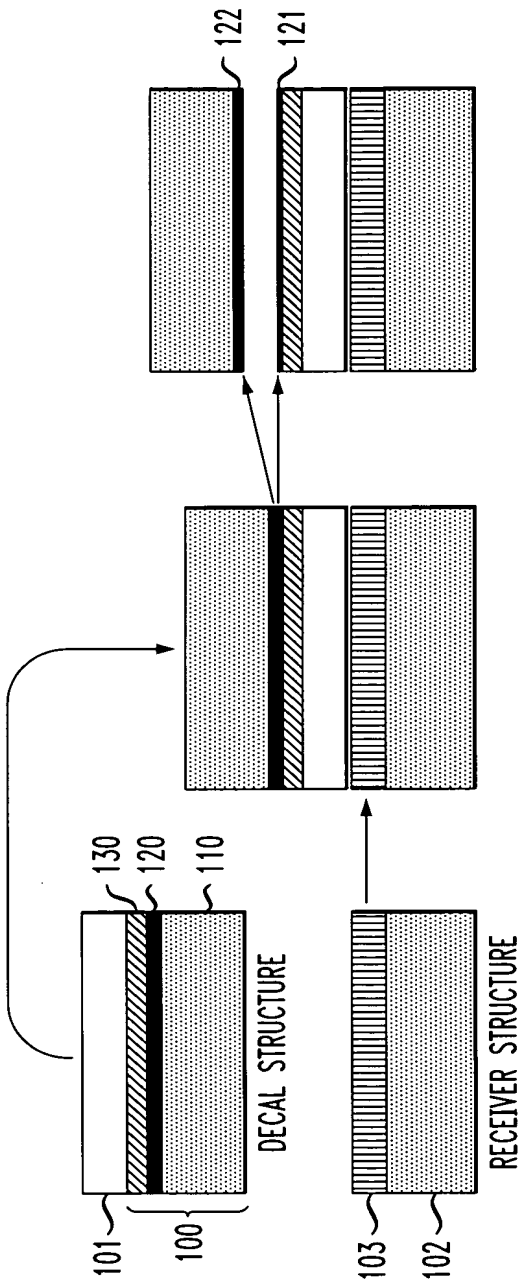


#1 STEP: BUILD OF DECAL  
AND RECEIVER STRUCTURES

#2 STEP: MATING OF DECAL  
AND RECEIVER STRUCTURES

#3 STEP: RELEASE OF CARRIER  
SUBSTRATE VIA PEELING

FIG. 5



#1 STEP: BUILD OF DECAL AND RECEIVER STRUCTURES

#2 STEP: MATING OF DECAL AND RECEIVER STRUCTURES

#3 STEP: RELEASE OF CARRIER SUBSTRATE VIA PEELING